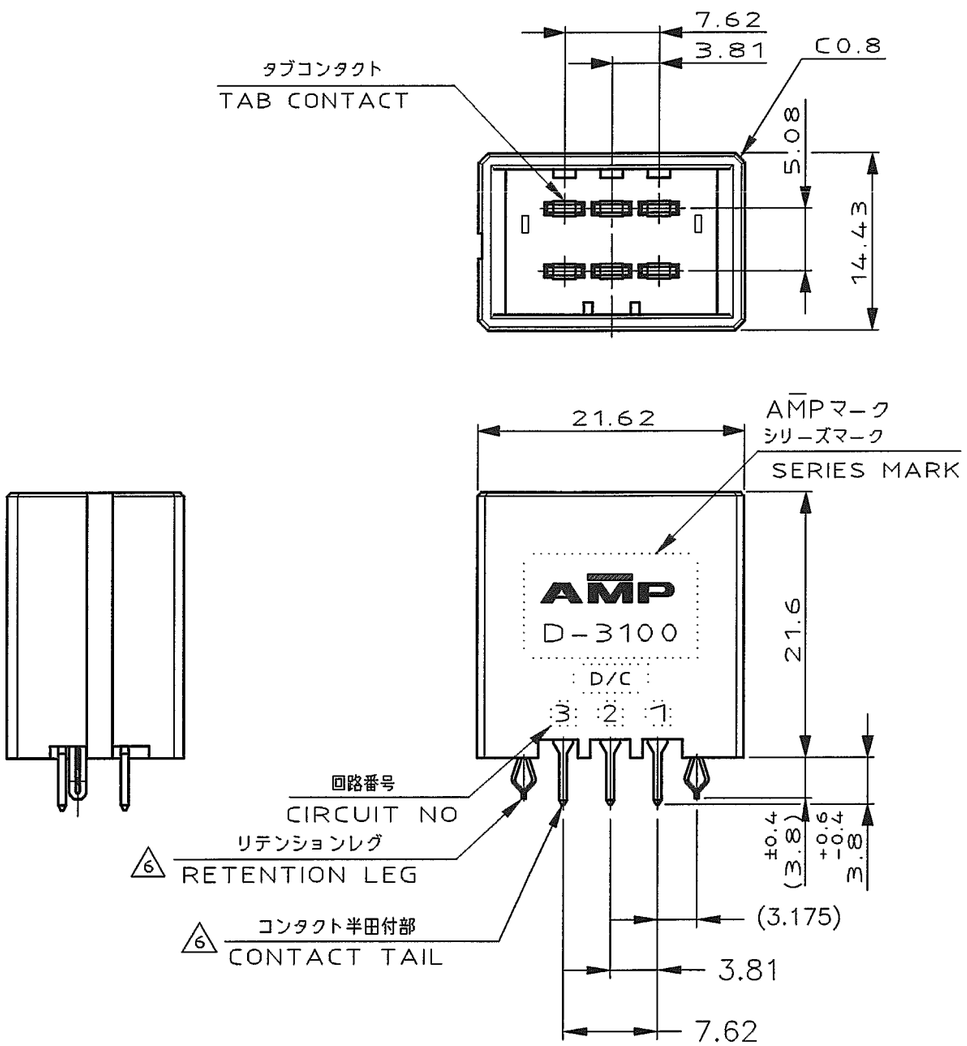
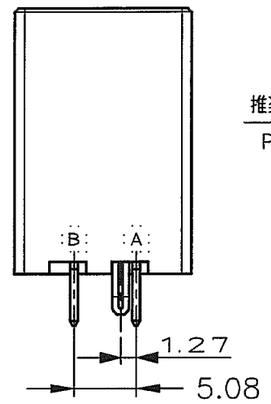
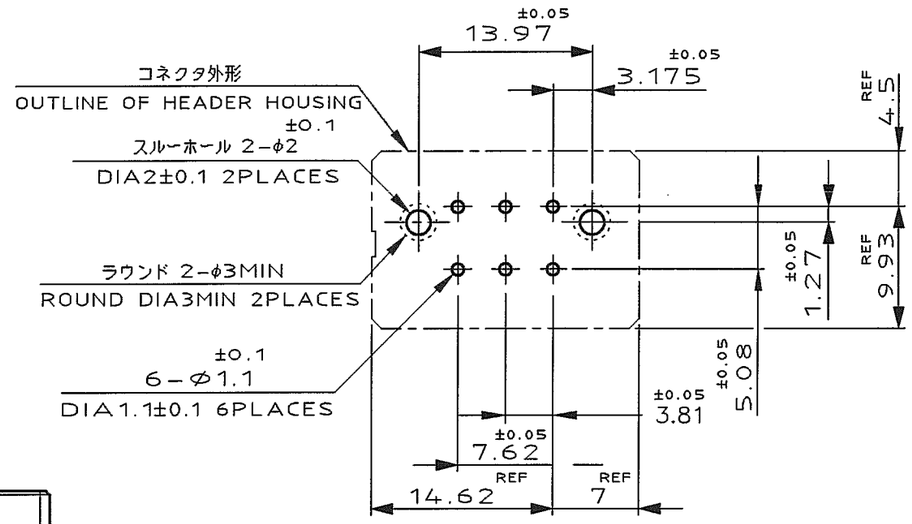
NUMBER 178323

3rd ANGLE PROJECTION

METRIC







推奨基板取付け穴寸法

PC 基板厚:1.6±0.1
(非累積公差)
(コネクタ搭載面)

RECOMEND PC BOARD HOLE PATTERN
PC BOARD THICKNESS:1.6±0.1
(NOT ACCUMULATE TOLERANCE)
(CONNECTOR MOUNT SIDE)

NOTES

1. MATERIAL:HOUSING:GLASS FILED THERMO PLASTIC,POLYESTER
CONTACT:COPPER ALLOY
RETENTION LEG:COPPER ALLOY

2. FINISH(CONTACT AREA):0.38μmMIN GOLD PLATING OVER Ni PLATING

3. FINISH(CONTACT AREA):0.76μmMIN GOLD PLATING OVER Ni PLATING

4. FINISH(CONTACT AREA):2.0 μmMIN TIN PLATED OVER NICKEL

~~5. FINISH(RETENTION LEG): TIN-LEAD PLATED (CONTACT TAIL) OVER NICKEL~~

6. FINISH(RETENTION LEG): TIN PLATED (CONTACT TAIL) OVER NICKEL

注記

1. 材料: ハウジング: ガラス入り熱可塑性ポリエステル樹脂
コンタクト: 銅合金
リテンションレグ: 銅合金

2. めっき: コンタクト: 全面Ni下地
接触部:0.38μm MIN金めっき

3. めっき: コンタクト: 全面Ni下地
接触部:0.76μm MIN金めっき

4. めっき: コンタクト: 全面Ni下地
接触部:2.0 μm MINスズめっき

~~5. めっき: リテンションレグとコンタクト半田付部 : ニッケル下地の上に半田めっき~~

6. めっき リテンションレグとコンタクト半田付部
: ニッケル下地の上にスズめっき

6 4		178323-5
6 3		178323-3
6 2		178323-2
(FINISH)		製品番号 (PART NO.)

LTR	REVISION RECORD		DR	CHK	DATE
D	REVISED	FJD0-0039-03	TS	S.M	6/2 '03
C	REVISED	FJD0-0097-03	TS	S.M	4/15 '03
B	REVISED	FJ00-0838-94	NM	S.M	7/4 '94
A	REDRAWN WITH CHANGE	FJ00-0480-94	NM	S.M	4/20 '94

Copyright © 1991
AMP(Japan) LTD.
ALL RIGHTS RESERVED.

tyco Electronics
Tyco Electoronics AMP K.K
Kawasaki,Japan

WIRE RANGE mm²(AWG -)	INSULATION DIA - mm	NAME DOUBLE ROW (D-3100) DYNAMIC CONN. 6POS. VERTICAL HDR. ASS'Y	
MATERIAL SEE NOTE 注記参照	FINISH SEE NOTE 注記参照	一般公差 (GENERAL TOLERANCE) 10未満 ±0.3; 10未満 30未満 ±0.4; 30未満100未満 ±0.5; 角度 ±3°	SIZE A3 / LOC J / NUMBER C-178323
DR. 15 FEB 91 N.Matsubara	DE. 15 FEB 91 N.Matsubara		SCALE 2-1 / REV. D / SHEET 1 OF 1
CHK. 21 MAY '91 M.Obata	APP. 21-MAY-'91 S.MINABE		

DIMENSIONS IN MILLIMETERS. DO NOT SCALE PRINT

PRINT DIST

AMP-J
REV.10/'83

(CUSTOMER DRAWING) 顧客用図面